# **MSC360SMA120S**

## 1200 V, 360 mΩ SiC N-Channel Power MOSFET

#### **Product Overview**

The silicon carbide (SiC) power MOSFET product line from Microsemi increases the performance over silicon MOSFET and silicon IGBT solutions while lowering the total cost of ownership for high-voltage applications. The MSC360SMA120S device is a 1200 V, 360 m $\Omega$  SiC MOSFET in a TO-268 (D3PAK) package.



1—Gate 2—Drain 3—Source Backside—Drain



#### **Features**

The following are key features of the MSC360SMA120S device:

- · Low capacitances and low gate charge
- · Fast switching speed due to low internal gate resistance (ESR)
- Stable operation at high junction temperature,  $T_{J(max)}$  = 175 °C
- · Fast and reliable body diode
- · Superior avalanche ruggedness
- RoHS compliant

#### **Benefits**

The following are benefits of the MSC360SMA120S device:

- · High efficiency to enable lighter, more compact system
- · Simple to drive and easy to parallel
- · Improved thermal capabilities and lower switching losses
- · Eliminates the need for external freewheeling diode
- Lower system cost of ownership

#### **Applications**

The MSC360SMA120S device is designed for the following applications:

- · PV inverter, converter, and industrial motor drives
- · Smart grid transmission and distribution
- Induction heating and welding
- · H/EV powertrain and EV charger
- Power supply and distribution

## 1. Device Specifications

This section shows the specifications of the MSC360SMA120S device.

### 1.1 Absolute Maximum Ratings

The following table shows the absolute maximum ratings of the MSC360SMA120S device.

**Table 1-1. Absolute Maximum Ratings** 

Symbol	Parameter	Ratings	Unit
V <sub>DSS</sub>	Drain source voltage	1200	V
I <sub>D</sub>	Continuous drain current at T <sub>C</sub> = 25 °C	11	Α
	Continuous drain current at T <sub>C</sub> = 100 °C	8	
I <sub>DM</sub>	Pulsed drain current <sup>1</sup>	27	
V <sub>GS</sub>	Gate-source voltage	23 to -10	V
P <sub>D</sub>	Total power dissipation at T <sub>C</sub> = 25 °C	71	W
	Linear derating factor	0.47	W/°C

#### Note:

1. Repetitive rating: pulse width and case temperature limited by maximum junction temperature.

The following table shows the thermal and mechanical characteristics of the MSC360SMA120S device.

**Table 1-2. Thermal and Mechanical Characteristics** 

Symbol	Characteristic/Test Conditions	Min	Тур	Max	Unit
$R_{\theta JC}$	Junction-to-case thermal resistance		1.4	2.1	°C/W
$T_J$	Operating junction temperature	<b>-</b> 55		175	°C
T <sub>STG</sub>	Storage temperature	<b>-</b> 55		150	°C
T <sub>L</sub>	Soldering temperature for 10 seconds (1.6 mm from case)			300	°C
Wt	Package weight		0.14		oz
			4.0		g

#### 1.2 Electrical Performance

The following table shows the static characteristics of the MSC360SMA120S device.  $T_J$  = 25 °C unless otherwise specified.

**Table 1-3. Static Characteristics** 

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_{D} = 100 \mu\text{A}$	1200			V
R <sub>DS(on)</sub>	Drain-source on resistance <sup>1</sup>	V <sub>GS</sub> = 20 V, I <sub>D</sub> = 5 A		360	450	mΩ
V <sub>GS(th)</sub>	Gate-source threshold voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.9	3.14		V

continued						
Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
$\Delta V_{GS(th)}/$ $\Delta T_J$	Threshold voltage coefficient	$V_{GS} = V_{DS}, I_D = 250 \mu A$		-5.5		mV/°C
I <sub>DSS</sub>	Zero gate voltage drain current	V <sub>DS</sub> = 1200 V, V <sub>GS</sub> = 0 V			100	μΑ
		$V_{DS}$ = 1200 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 °C			500	
I <sub>GSS</sub>	Gate-source leakage current	V <sub>GS</sub> = 20 V/–10 V			±100	nA

#### Note:

1. Pulse test: pulse width < 380 μs, duty cycle < 2%.

The following table shows the dynamic characteristics of the MSC360SMA120S device.  $T_J$  = 25 °C unless otherwise specified.

**Table 1-4. Dynamic Characteristics** 

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
C <sub>iss</sub>	Input capacitance	$V_{GS} = 0 \text{ V}, V_{DD} = 1000 \text{ V}, V_{AC} = 25$		255		pF
C <sub>rss</sub>	Reverse transfer capacitance	mV, <i>f</i> = 200 kHz		2		
C <sub>oss</sub>	Output capacitance			25		
Qg	Total gate charge	$V_{GS} = -5 \text{ V/20 V}, V_{DD} = 800 \text{ V}, I_{D} =$		21		nC
Q <sub>gs</sub>	Gate-source charge	5 A		6		
Q <sub>gd</sub>	Gate-drain charge			7		
t <sub>d(on)</sub>	Turn-on delay time	$V_{DD} = 800 \text{ V}, V_{GS} = -5 \text{ V}/20 \text{ V}, I_{D} =$		12		ns
t <sub>r</sub>	Voltage rise time	7 A, $R_{g(ext)}$ = 16.0 $\Omega$ , Freewheeling diode = MSC360SMA120S ( $V_{GS}$ =		14		
t <sub>d(off)</sub>	Turn-off delay time	–5 V); reference Fig. 1-20		14		
t <sub>f</sub>	Voltage fall time			8		
E <sub>on</sub>	Turn-on switching energy			128		μJ
E <sub>off</sub>	Turn-off switching energy			15		
t <sub>d(on)</sub>	Turn-on delay time	V <sub>DD</sub> = 800 V, V <sub>GS</sub> = -5		24		ns
t <sub>r</sub>	Voltage rise time	V/20 V, $I_D$ = 7 A, $R_{g(ext)}$ = 16.0 Ω, Freewheeling diode =		15		
t <sub>d(off)</sub>	Turn-off delay time	MSC010SDA120B; reference Fig.		14		
t <sub>f</sub>	Voltage fall time	1-20		10		
E <sub>on</sub>	Turn-on switching energy			129		μJ
E <sub>off</sub>	Turn-off switching energy			12		
ESR	Equivalent series resistance	f = 1 MHz, 25 mV, drain short		3.7		Ω
SCWT	Short circuit withstand time	V <sub>DS</sub> = 960 V, V <sub>GS</sub> = 20 V		2.6		μs
E <sub>AS</sub>	Avalanche energy, single pulse	V <sub>DS</sub> = 150 V, I <sub>D</sub> = 5 A		100		mJ

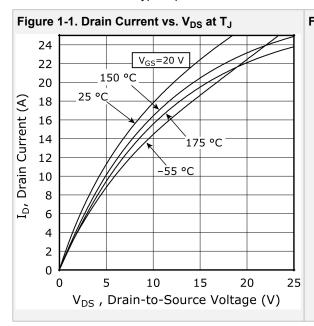
The following table shows the body diode characteristics of the MSC360SMA120S device.  $T_J$  = 25 °C unless otherwise specified.

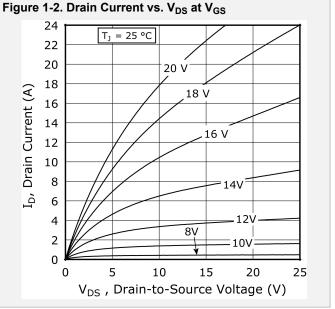
**Table 1-5. Body Diode Characteristics** 

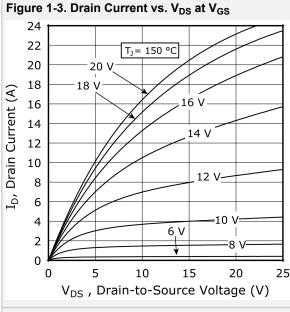
Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
V <sub>SD</sub>	Diode forward voltage	I <sub>SD</sub> = 5 A, V <sub>GS</sub> = 0 V		4.0		V
		I <sub>SD</sub> = 5 A, V <sub>GS</sub> = -5 V		4.2		
t <sub>rr</sub>	Reverse recovery time	$I_{SD} = 7 \text{ A}, V_{GS} = -5 \text{ V}, V_{DD} =$		29		ns
Q <sub>rr</sub>	Reverse recovery charge	800 V, dl/dt = $-760$ A/μs, Drive Rg = $16.0$ Ω		59		nC
I <sub>RRM</sub>	Reverse recovery current			3.4		Α

### 1.3 Typical Performance Curves

This section shows the typical performance curves of the MSC360SMA120S device.







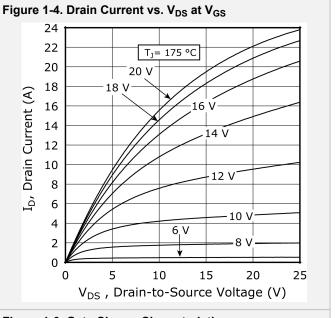


Figure 1-5. R<sub>DS(on)</sub> vs. Junction Temperature

2.0

1.8

Normalized to 25 °C V<sub>GS</sub> = 20 V at 5 A

1.6

1.6

1.6

0.8

0.8

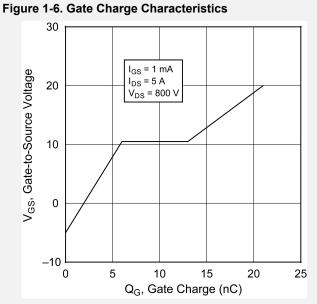
0.6

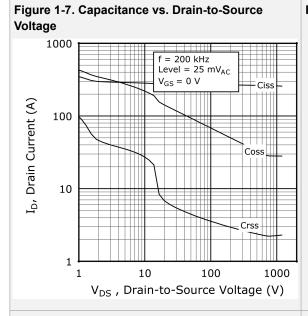
0.4

0.2

-50 -25 0 25 50 75 100 125 150 175

T<sub>J</sub>, Junction Temperature (°C)





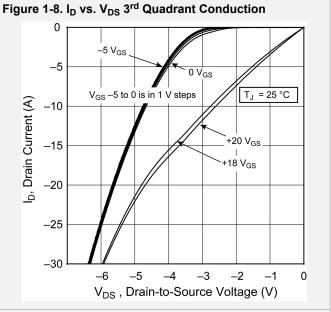


Figure 1-9. I<sub>D</sub> vs. V<sub>DS</sub> 3<sup>rd</sup> Quadrant Conduction

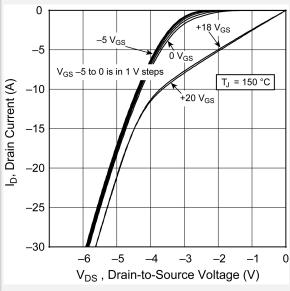
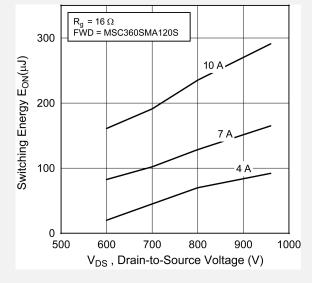


Figure 1-10. Switching Energy Eon vs.  $V_{DS} \& I_{D}$ 



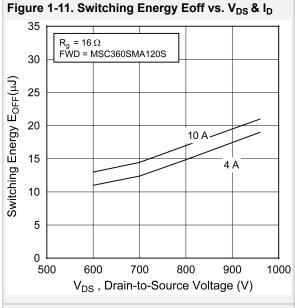
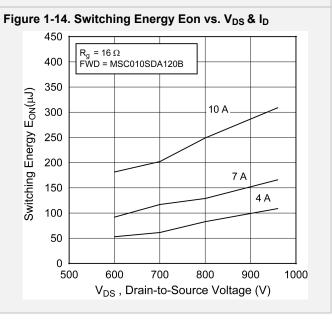
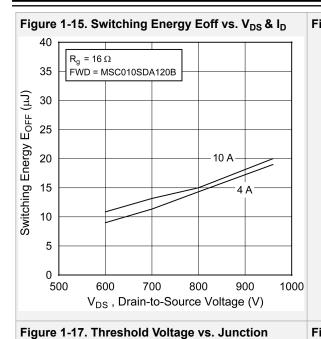
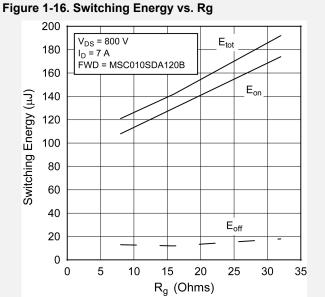


Figure 1-12. Switching Energy vs. Rq  $V_{DS} = 800 \text{ V}$  $\mathsf{E}_{tot}$  $I_D = 7 A$ 160 FWD = MSC360SMA120S 140  $E_{on}$ Switching Energy (µJ) 120 100 80 60 40  $\mathsf{E}_{\mathsf{off}}$ 20 0 0 5 10 15 20 25 30 35 R<sub>g</sub> (Ohms)

Figure 1-13. Switching Energy vs. Temperature V<sub>DS</sub> = 800 V I<sub>D</sub> = 7 A 250  $R_a = 16 \Omega$ FWD = MSC360SMA120S  $\mathsf{E}_{\mathsf{tot}}$ Switching Energy (µJ) 200  $E_{on}$ 150 100 50 E<sub>off</sub> 0 100 200 T<sub>J</sub>, Junction Temperature (°C)







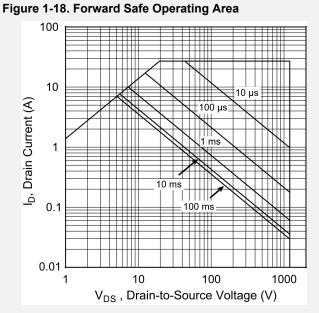
Temp.

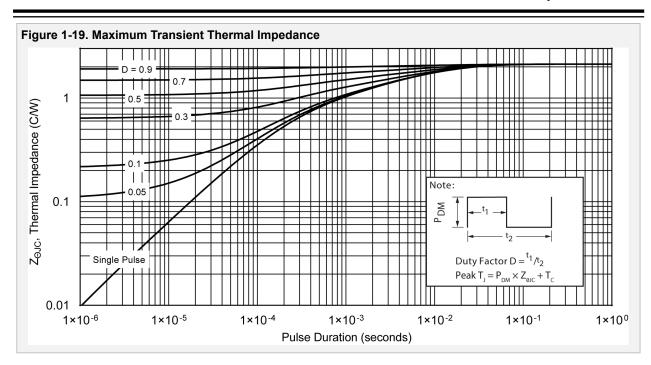
4.5

4.0

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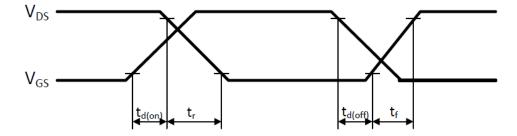
T<sub>J</sub>, Junction Temperature (°C)





The following figure shows the switching waveform diagram of the MSC360SMA120S device.

Figure 1-20. Switching Waveform



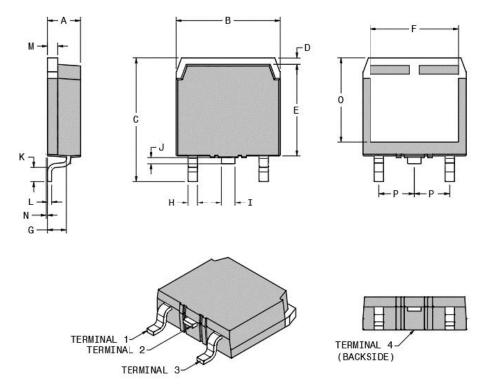
## 2. Package Specification

This section shows the package specification of the MSC360SMA120S device.

### 2.1 Package Outline Drawing

The following figure illustrates the TO-268 package outline of the MSC360SMA120S device.

Figure 2-1. Package Outline Drawing



The following table shows the TO-268 dimensions and should be used in conjunction with the package outline drawing.

Table 2-1. TO-268 Dimensions

Symbol	Min (mm)	Max (mm)	Min (in.)	Max (in.)
Α	4.90	5.10	0.193	0.201
В	15.85	16.20	0.624	0.638
С	18.70	19.10	0.736	0.752
D	1.00	1.025	0.039	0.049
E	13.80	14.00	0.543	0.551
F	13.30	13.60	0.524	0.535
G	2.70	2.90	0.106	0.114
Н	1.15	1.45	0.045	0.057
I	1.95	2.21	0.077	0.087

## MSC360SMA120S

## **Package Specification**

continued					
Symbol	Min (mm)	Max (mm)	Min (in.)	Max (in.)	
J	0.94	1.40	0.037	0.055	
K	2.40	2.70	0.094	0.106	
L	0.40	0.60	0.016	0.024	
M	1.45	1.60	0.057	0.063	
N	0.00	0.018	0.00	0.007	
0	12.40	12.70	0.488	0.500	
Р	5.45 BSC (nom.)		0.215 BSC (nom.)		
Terminal 1	Gate				
Terminal 2	Drain				
Terminal 3	Source				
Terminal 4	Drain				

## 3. Revision History

Table 3-1. Revision History

Revision	Date	Description
Α	01/2022	Document created.

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